



# SOT1831-2

HLQFN26, thermal enhanced low profile quad flat package, no leads, 1 mm pitch, 10 mm x 6 mm x 1.365 mm body

28 December 2020

Package information

## 1 Package summary

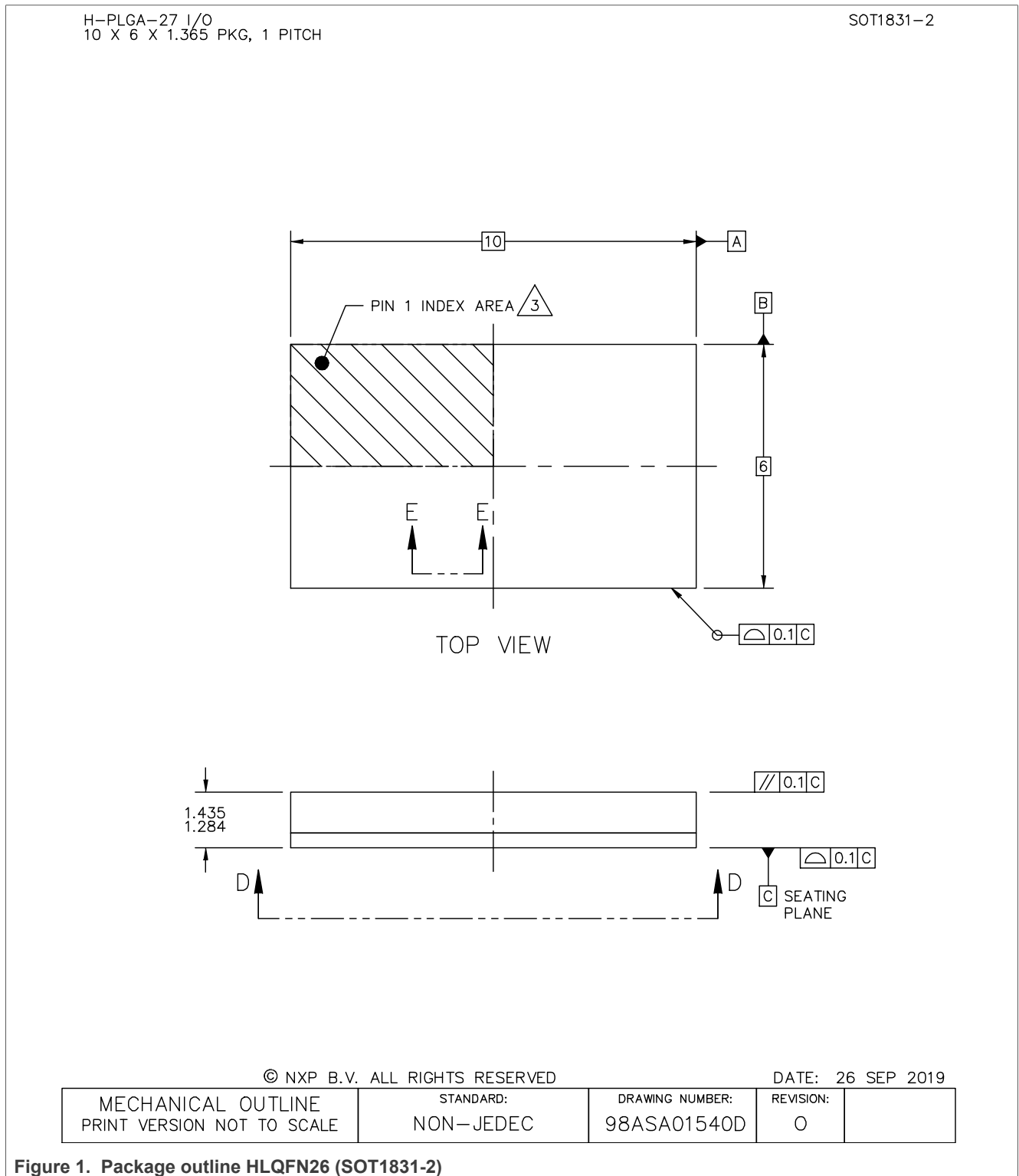
<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HLQFN26
<b>Package style descriptive code</b>	HLQFN (thermal enhanced low profile quad flatpack; no leads)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	26-09-2019
<b>Manufacturer package code</b>	98ASA01540D

Table 1. Package summary

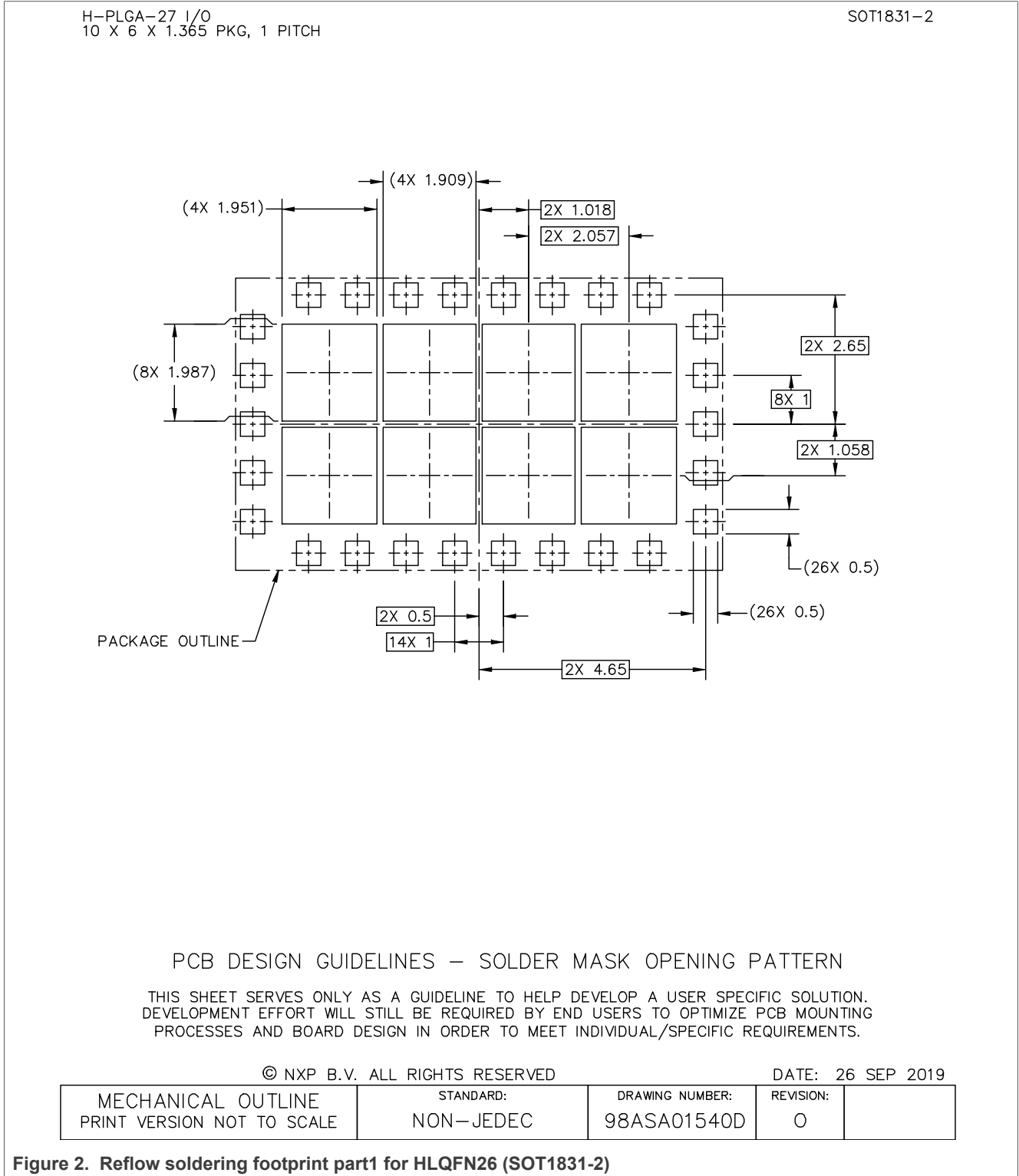
Parameter	Min	Nom	Max	Unit
package length	9.9	10	10.1	mm
package width	5.9	6	6.1	mm
package height	1.284	1.365	1.435	mm
nominal pitch	-	1	-	mm
actual quantity of termination	-	26	-	



2 Package outline



3 Soldering



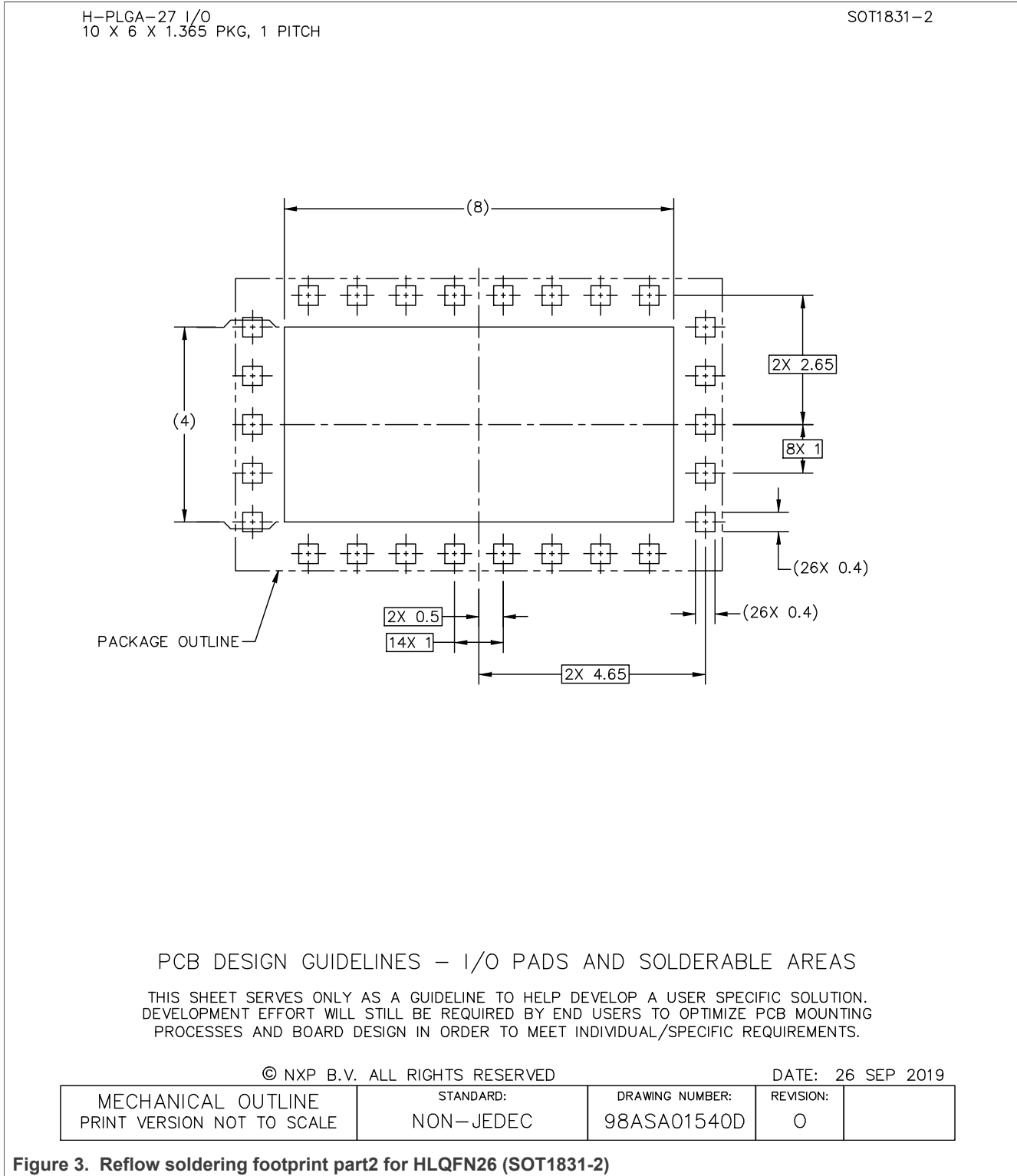


Figure 3. Reflow soldering footprint part2 for HLQFN26 (SOT1831-2)

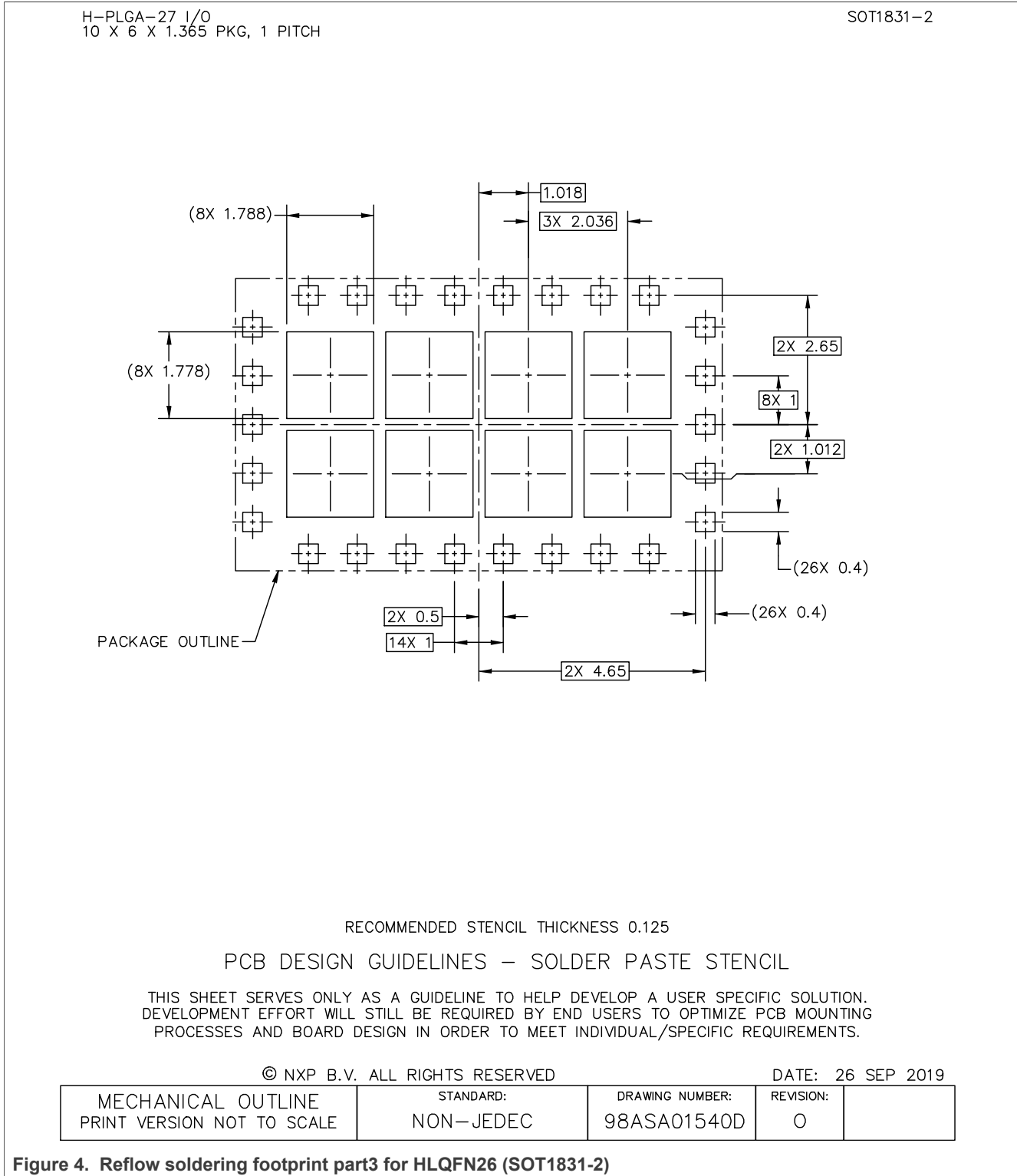


Figure 4. Reflow soldering footprint part3 for HLQFN26 (SOT1831-2)

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H-PLGA-27 I/O  
10 X 6 X 1.365 PKG, 1 PITCH

SOT1831-2

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. DIMENSION APPLIES TO ALL LEADS AND FLAG.
5. THE BOTTOM VIEW SHOWS THE SOLDERABLE AREA OF THE PADS. THE CENTER PAD (PIN 27) IS SOLDER MASK DEFINED. SOME PERIPHERAL PADS ARE SOLDER MASK DEFINED (SMD) AND OTHERS ARE NON-SOLDERMASK DEFINED (NSMD).

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DATE: 26 SEP 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01540D	REVISION: 0	
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Figure 5. Package outline note HLQFN26 (SOT1831-2)

## 4 Legal information

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